

#### FEATURES

- · Glass passivated
- High maximum operating temperature
- · Low leakage current
- Excellent stability
- Guaranteed avalanche energy absorption capability
- Available in ammo-pack
- Also available with preformed leads for easy insertion.

#### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>RRM</sub>	repetitive peak reverse voltage				
	ВҮМЗ6А		_	200	V
	ВҮМ36В		_	400	V
	BYM36C		_	600	V
	BYM36D		_	800	V
	BYM36E		_	1000	V
	BYM36F		_	1200	V
	BYM36G		_	1400	V
V <sub>R</sub>	continuous reverse voltage				
	ВҮМЗ6А		_	200	V
	ВҮМ36В		_	400	V
	BYM36C		_	600	V
	BYM36D		_	800	V
	BYM36E		_	1000	V
	BYM36F		-	1200	V
	BYM36G		_	1400	V
I <sub>F(AV)</sub>	average forward current	$T_{tp} = 55 \text{ °C}; \text{ lead length} = 10 \text{ mm};$			
	BYM36A to C	see Figs 2; 3 and 4 averaged over any 20 ms period; see also Figs 14; 15 and 16	-	3.0	A
	BYM36D and E		_	2.9	A
	BYM36F and G		_	2.9	A
I <sub>F(AV)</sub>	average forward current	T <sub>amb</sub> = 65 °C; PCB mounting (see			
	BYM36A to C	Fig.25); see Figs 5; 6 and 7 averaged over any 20 ms period; see also Figs 14; 15 and 16	-	1.25	A
	BYM36D and E		-	1.20	A
	BYM36F and G		_	1.15	A

#### DESCRIPTION

Rugged glass SOD64 package, using a high temperature alloyed construction. This package is hermetically sealed and fatigue free as coefficients of expansion of all used parts are matched.

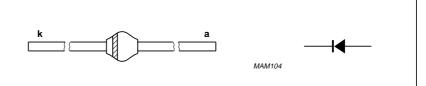


Fig.1 Simplified outline (SOD64) and symbol.



SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I <sub>FRM</sub>	repetitive peak forward current	T <sub>tp</sub> = 55 °C; see Figs 8; 9 and 10			
	BYM36A to C		_	37	A
	BYM36D and E		_	33	A
	BYM36F and G		_	27	A
I <sub>FRM</sub>	repetitive peak forward current T <sub>amb</sub> = 65 °C; see Figs 11; 12 and 13				
	BYM36A to C		_	13	A
	BYM36D and E		_	11	A
	BYM36F and G		_	10	A
I <sub>FSM</sub>	non-repetitive peak forward current	t = 10 ms half sine wave; $T_j = T_{j max}$ prior to surge; $V_R = V_{RRMmax}$	_	65	A
E <sub>RSM</sub>	non-repetitive peak reverse avalanche energy	L = 120 mH; $T_j = T_{j max}$ prior to surge; inductive load switched off	_	10	mJ
T <sub>stg</sub>	storage temperature		-65	+175	°C
Tj	junction temperature	see Figs 17 and 18	-65	+175	°C

#### ELECTRICAL CHARACTERISTICS

 $T_i = 25 \ ^{\circ}C$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>F</sub>	forward voltage	$I_F = 3 A; T_j = T_{j max};$				
	BYM36A to C	see Figs 19; 20 and 21	-	_	1.22	V
	BYM36D and E		-	-	1.28	V
	BYM36F and G		-	-	1.24	V
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 3 A;				
	BYM36A to C	see Figs 19; 20 and 21	-	-	1.60	V
	BYM36D and E		-	_	1.78	V
	BYM36F and G		-	-	1.57	V
V <sub>(BR)R</sub>	reverse avalanche breakdown voltage	I <sub>R</sub> = 0.1 mA				
	BYM36A		300	_	_	V
	BYM36B		500	_	_	V
	BYM36C		700	_	-	V
	BYM36D		900	_	-	V
	BYM36E		1100	_	-	V
	BYM36F		1300	_	-	V
	BYM36G		1500	-	-	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = V <sub>RRMmax</sub> ; see Fig.22	-	_	5	μA
		$V_R = V_{RRMmax};$ T <sub>j</sub> = 165 °C; see Fig.22	-	_	150	μA



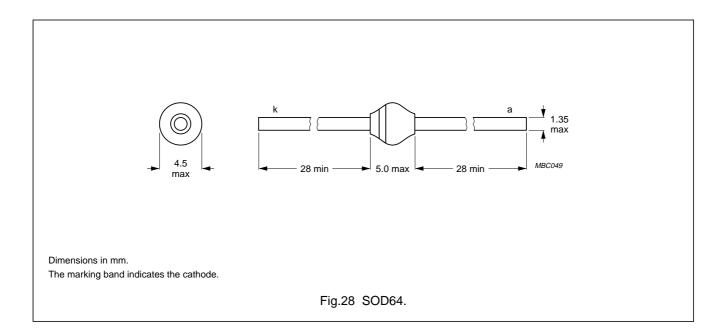
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
t <sub>rr</sub>	reverse recovery time	when switched from $I_F = 0.5 \text{ A to } I_R = 1 \text{ A}$ ; measured at $I_R = 0.25 \text{ A}$ ; see Fig. 26				
	BYM36A to C		_	_	100	ns
	BYM36D and E		_	_	150	ns
	BYM36F and G		_	-	250	ns
C <sub>d</sub>	diode capacitance	$f = 1 MHz; V_R = 0 V;$ see Figs 23 and 24				
	BYM36A to C		_	85	_	pF
	BYM36D and E		_	75	-	pF
	BYM36F and G		_	65	-	pF
$\frac{dI_R}{dt}$	maximum slope of reverse recovery current	when switched from $I_F = 1 \text{ A to } V_R \ge 30 \text{ V and}$				
	BYM36A to C	$dI_F/dt = -1 A/\mu s;$	_	_	7	A/μs
	BYM36D and E	see Fig.27	_	_	6	A/μs
	BYM36F and G		_	_	5	A/µs

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-tp</sub>	thermal resistance from junction to tie-point	lead length = 10 mm	25	K/W
R <sub>th j-a</sub>	thermal resistance from junction to ambient	note 1	75	K/W

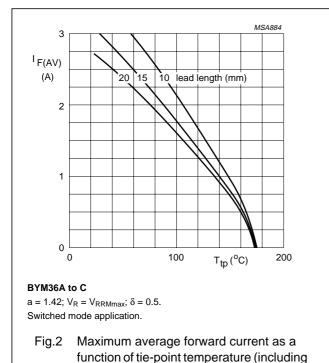
#### Note

1. Device mounted on an epoxy-glass printed-circuit board, 1.5 mm thick; thickness of Cu-layer ≥40 μm, see Fig.25. For more information please refer to the *"General Part of associated Handbook"*.





#### **GRAPHICAL DATA**



losses due to reverse leakage).

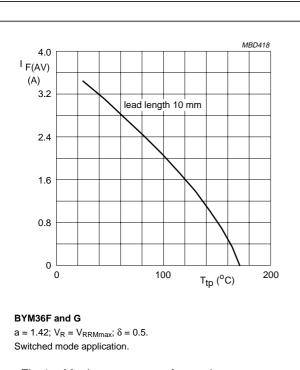
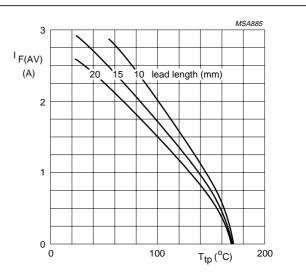


Fig.4 Maximum average forward current as a function of tie-point temperature (including losses due to reverse leakage).



# BYM36D and E $a = 1.42; V_R = V_{RRMmax}; \delta = 0.5.$

Switched mode application.

Fig.3 Maximum average forward current as a function of tie-point temperature (including losses due to reverse leakage).

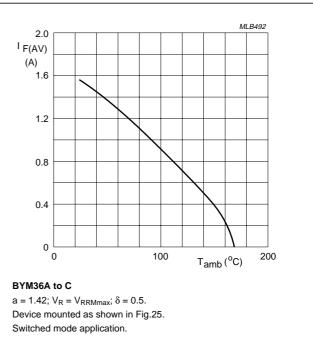


Fig.5 Maximum average forward current as a function of ambient temperature (including losses due to reverse leakage).



